# **Triple Buffer with Open Drain Outputs**

The NL37WZ07 is a high performance triple buffer with open drain outputs operating from a 2.3 to 5.5 V supply.

The internal circuit is composed of multiple stages, including an open drain output which provides the capability to set output switching level. This allows the NL37WZ07 to be used to interface 5 V circuits to circuits of any voltage between V<sub>CC</sub> and 7 V using an external resistor and power supply.

- Extremely High Speed: tpD 2.5 ns (typical) at  $V_{CC} = 5 \text{ V}$
- Designed for 2.3 V to 5.5 V V<sub>CC</sub> Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability with 5 V TTL Logic with  $V_{CC} = 3 \text{ V}$
- LVCMOS Compatible
- 24 mA Output Sink Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72

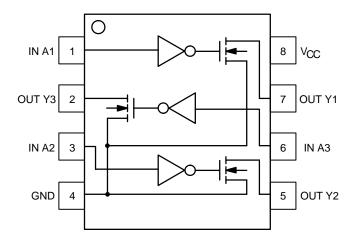


Figure 1. Pinout

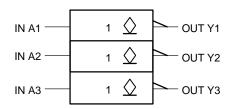


Figure 2. Logic Symbol



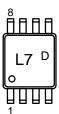
# ON Semiconductor™

http://onsemi.com





US8 US SUFFIX CASE 493



**MARKING** 

L7 = Device Code D = Date Code

## **PIN ASSIGNMENT**

1	IN A1
2	OUT Y3
3	IN A2
4	GND
5	OUT Y2
6	IN A3
7	OUT Y1
8	Vcc

## **FUNCTION TABLE**

Y Output
L
Z

## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

## **MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit
VCC	DC Supply Voltage		-0.5  to  +7.0	V
VI	DC Input Voltage		-0.5  to  +7.0	V
VO	DC Output Voltage		-0.5  to  +7.0	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	-50	mA
lok	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
IO	DC Output Sink Current		±50	mA
ICC	DC Supply Current per Supply Pin		±100	mA
IGND	DC Ground Current per Ground Pin		±100	mA
TSTG	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature under Bias		+150	°C
$\theta$ JA	Thermal Resistance	(Note 1)	250	°C/W
PD	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
FR	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
VESD		Human Body Model (Note 2) Machine Model (Note 3) Irged Device Model (Note 4)	> 2000 > 150 N/A	V

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

- Tested to EIA/JESD22-A114-A.
   Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
VCC	Supply Voltage	Operating Data Retention Only	2.3 1.5	5.5 5.5	V
VI	Input Voltage	(Note 5)	0	5.5	V
٧o	Output Voltage	(HIGH or LOW State)	0	Vcc	V
T <sub>A</sub>	Operating Free–Air Temperature		-40	+ 85	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 \text{ V } \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V } \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V } \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

5. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

## DC ELECTRICAL CHARACTERISTICS

			VCC	T <sub>A</sub> = 25°C		С	-40°C ≤	<b>T<sub>A</sub> ≤ 85°C</b>	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
VIH	High-Level Input Voltage		2.3 to 5.5	0.7 V <sub>CC</sub>			0.7 V <sub>CC</sub>		V
VIL	Low-Level Input Voltage		2.3 to 5.5			0.3 V <sub>C</sub> C		0.3 V <sub>CC</sub>	V
ILKG	Z-State Output Leakage Current	$V_{IN} = V_{IL}$ $V_{OUT} = V_{CC}$ or GND	2.3 to 5.5			±5.0		±10.0	μΑ
VOL	Low-Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 to 5.5			0.1		0.1	V
	$V_{IN} = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 8 mA	2.3		0.20	0.3		0.3	
		I <sub>OL</sub> = 12 mA	2.7		0.22	0.4		0.4	
		I <sub>OL</sub> = 16 mA	3.0		0.28	0.4		0.4	
		I <sub>OL</sub> = 24 mA	3.0		0.38	0.55		0.55	
		I <sub>OL</sub> = 32 mA	4.5		0.42	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	$V_{IN}$ or $V_{OUT} = V_{CC}$ or GND	0 to 5.5			±0.1		±1.0	μΑ
loff	Power Off–Output Leakage Current	V <sub>OUT</sub> = 5.5 V	0			1		10	μΑ
ICC	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

# AC ELECTRICAL CHARACTERISTICS $t_R=t_F$ = 2.5 ns; $C_L$ = 50 pF; $R_L$ = 500 $\Omega$

				T <sub>A</sub> = 25°C		-40°C ≤T <sub>A</sub> ≤ 85°C			
Symbol	Parameter	Condition	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
tPZL	Propagation Delay	$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4	ns
	(Figure 3 and 4)	$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	$3.3 \pm 0.3$	0.8	2.9	4.4	0.8	4.8	
		$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	$5.0 \pm 0.5$	0.5	2.3	3.5	0.5	3.9	
tPLZ	Propagation Delay	$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	$2.5 \pm 0.2$	1.2	2.8	5.8	1.2	6.4	ns
(Figure 3 and 4)		$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	$3.3 \pm 0.3$	0.8	2.1	4.4	0.8	4.8	
		$R_{L} = R_{1} = 500 \Omega, C_{L} = 50 pF$	$5.0 \pm 0.5$	0.5	1.4	3.5	0.5	3.9	

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	2.5	pF
COUT	Output Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	4.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	10 MHz, $V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	4.0	pF

<sup>6.</sup> Cp<sub>D</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

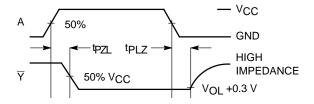
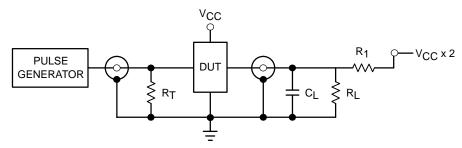


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

# **DEVICE ORDERING INFORMATION**

	Device Nomenclature							
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Package Type	Tape and Reel Size
NL37WZ07US	NL	3	7	WZ	07	US	US8	178 mm (7") 3000 Unit

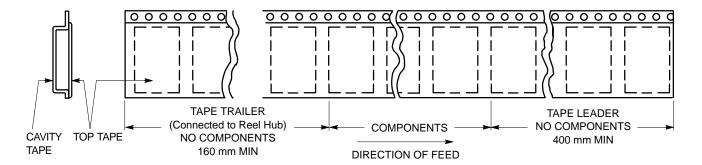


Figure 5. Tape Ends for Finished Goods

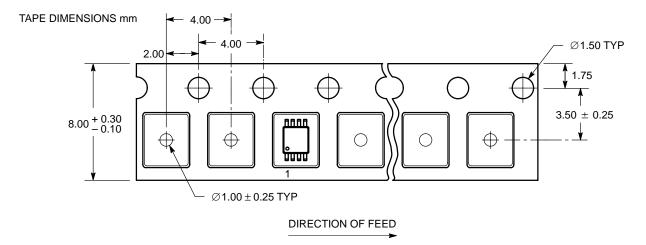


Figure 6. US8 Reel Configuration/Orientation

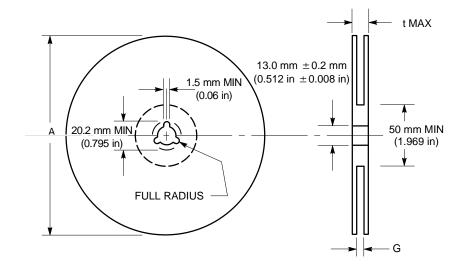
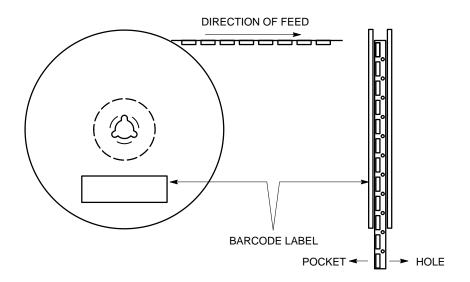


Figure 7. Reel Dimensions

# **REEL DIMENSIONS**

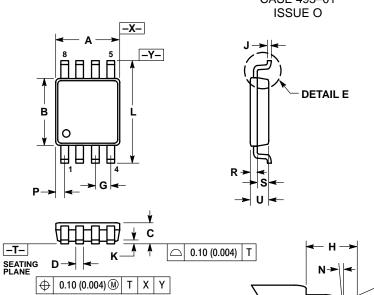
Tape Size	T and R Suffix	A Max	G	t Max
8 mm	US	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)



**Figure 8. Reel Winding Direction** 

## **PACKAGE DIMENSIONS**

# US8 **US SUFFIX** CASE 493-01





**R 0.10 TYP** 

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETERS

  3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH. PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055") PER SIDE.

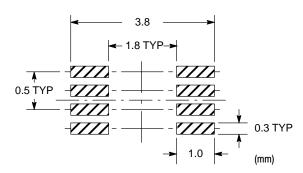
  4. DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION SHALL NOT E3XCEED 0.140 (0.0055") PER SIDE.

  5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800 INCH).

- INCH).

  6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0002").

	MILLIN	IETERS	INCHES		
DIM	MIN MAX		MIN	MAX	
Α	1.90	2.10	0.075	0.083	
В	2.20	2.40	0.087	0.094	
С	0.60	0.90	0.024	0.035	
D	0.17	0.25	0.007	0.010	
F	0.20	0.35	0.008	0.014	
G	0.50	BSC	0.020	) BSC	
Н	0.40	REF	0.016	REF	
J	0.10	0.18	0.004	0.007	
K	0.00	0.10	0.000	0.004	
L	3.00	3.20	0.118	0.126	
M	0 °	6 °	0 °	6°	
N	5°	10 °	5 °	10 °	
P	0.28	0.44	0.011	0.017	
R	0.23	0.33	0.009	0.013	
S	0.37	0.47	0.015	0.019	
U	0.60	0.80	0.024	0.031	
٧	0.12	BSC	0.005	BSC	



**DETAIL E** 

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